

L Number	Hits	Search Text	DB	Time stamp
20	1	5864278.pn.	USPAT; US-PGPUB	2003/06/06 13:01
-	17	(temperature\$1dependent).ti. and (marcel).in.	USPAT; US-PGPUB	2003/05/31 11:24
-	395	(temperature\$1dependent).ti. ahesive and stamp\$3 and heat\$3 and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:31
-	12	((temperature\$1dependent).ti. ahesive and stamp\$3 and heat\$3 and seal\$3) and (moisture dust)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:27
-	1	temperature\$1dependent and ahesive and heat\$3 and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:51
-	2	6282409.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:34
-	2	6051169.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:34
-	1502	stamp\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:11
-	8	(stamp\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and temperature\$1dependent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:54
-	553	(stamp\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and join\$3 and clos\$3 and cur\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 11:59
-	197	((stamp\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and join\$3 and clos\$3 and cur\$3) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:06
-	185	((stamp\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and join\$3 and clos\$3 and cur\$3) and switch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:06
-	4528	join\$3 and clos\$3 and cur\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:12
-	904	(join\$3 and clos\$3 and cur\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and protect\$3 and connect\$3 and switch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:13
-	218	((join\$3 and clos\$3 and cur\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and protect\$3 and connect\$3 and switch\$3) and press\$3 and electric\$4 and dip\$4 and fill\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:16

-	107	((join\$3 and clos\$3 and cur\$3 and (moisture dust) and cover\$3 and adhesive and heat\$3 and seal\$3) and protect\$3 and connect\$3 and switch\$3) and press\$3 and electric\$4 and dip\$4 and fill\$3) and circuit\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 12:26
-	14	adhesive with cur\$3 and join\$3 and hous\$3 and cover\$3 and heat\$3 and seal\$3 and (dust moisture) and clos\$3 and switch\$3 with mechanism	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 13:36
-	2	"19757023"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 13:40
-	0	"29605048"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 13:44
-	8	"4139091"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/31 13:44
-	43	29/622,623.ccls. and 337/\$.ccls. and adhesive	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:34
-	45	29/622,623.ccls. and adhesive and seal\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:37
-	4	29/dig?1.ccls. and adhesive and seal\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:38
-	2	337/33\$.ccls. and adhesive and seal\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:39
-	94	337/\$.ccls. and adhesive and seal\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:42
-	369	156/292,293,305.ccls. and adhesive and seal\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:42
-	21	(156/292,293,305.ccls. and adhesive and seal\$3 and cur\$3) and switch\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:45
-	94	337/\$.ccls. and switch\$3 and adhesive and bimetal\$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:46
-	33	(337/\$.ccls. and switch\$3 and adhesive and bimetal\$4) and cover\$3 and cur\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:48
-	69	(337/\$.ccls. and switch\$3 and adhesive and bimetal\$4) and cover\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/06/02 15:48